

Specification for

Oxygen-free high-conductivity copper for electronic tubes and semiconductor devices

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Cooperating organizations

The Electronic Components Standards Committee, under whose direction this British Standard was prepared, consists of representatives from the following Government department and scientific and industrial organizations:

- British Electrical and Allied Manufacturers' Association (BEAMA)
- Electricity Supply Industry in England and Wales
- Electronic Components Industry Federation*
- Electronic Engineering Association*
- Institution of Electronic and Radio Engineers*
- Ministry of Defence*
- National Supervising Inspectorate*
- Post Office*
- Society of British Aerospace Companies Limited
- Telecommunication Engineering and Manufacturing Association (TEMA)
- Trades Union Congress

The organizations marked with an asterisk in the above list, together with the following, were directly represented on the committee entrusted with the preparation of this British Standard:

- British Non-Ferrous Metals Federation
- Scientific Instrument Manufacturers' Association
- United Kingdom Atomic Energy Authority

This British Standard, having been prepared under the direction of the Electronic Components Standards Committee, was published under the authority of the Executive Board on 30 November 1978

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Foreword

This revised British Standard has been prepared under the direction of the Electronic Components Standards Committee from information provided by the Electronic Components Industries Federation and the British Non-Ferrous Metals Federation. The producers of the raw material and of the fabricated forms also cooperated in the preparation of this standard. There is no requirement for resistivity or conductivity to be measured, as copper in compliance with this standard has been found to have an adequate conductivity for use in electronic tubes and semiconductor devices.

In the preparation of this standard attention has been paid to the requirements of ISO standards ISO 2624, ISO 2626 and ISO 4746.

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, pages 1 to 6, an inside back cover and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.